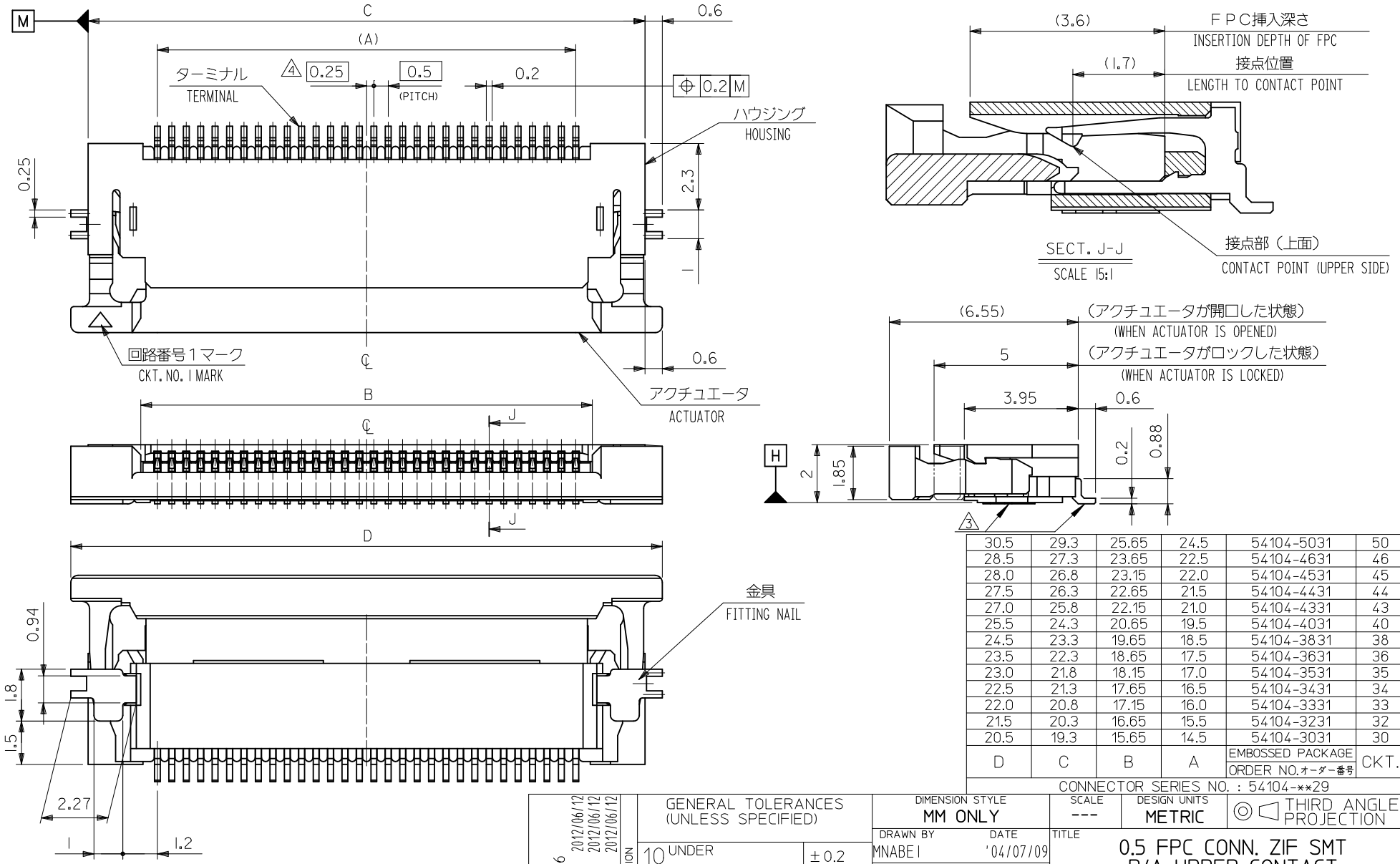


D	C	B	A	EMBOSSED PACKAGE ORDER NO. オーダー番号	CKT.
30.5	29.3	25.65	24.5	54104-5031	50
28.5	27.3	23.65	22.5	54104-4631	46
28.0	26.8	23.15	22.0	54104-4531	45
27.5	26.3	22.65	21.5	54104-4431	44
27.0	25.8	22.15	21.0	54104-4331	43
25.5	24.3	20.65	19.5	54104-4031	40
24.5	23.3	19.65	18.5	54104-3831	38
23.5	22.3	18.65	17.5	54104-3631	36
23.0	21.8	18.15	17.0	54104-3531	35
22.5	21.3	17.65	16.5	54104-3431	34
22.0	20.8	17.15	16.0	54104-3331	33
21.5	20.3	16.65	15.5	54104-3231	32
20.5	19.3	15.65	14.5	54104-3031	30

CONNECTOR SERIES NO. : 54104-**29

REVISED
EC NO: J2012-1496 2012/06/12
DRWN:KNAGUMO 2012/06/12
CH'KD:KTAKAHASHI 2012/06/12
APPR:KMORIKAWA 2012/06/12
DESCRIPTION
REV

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

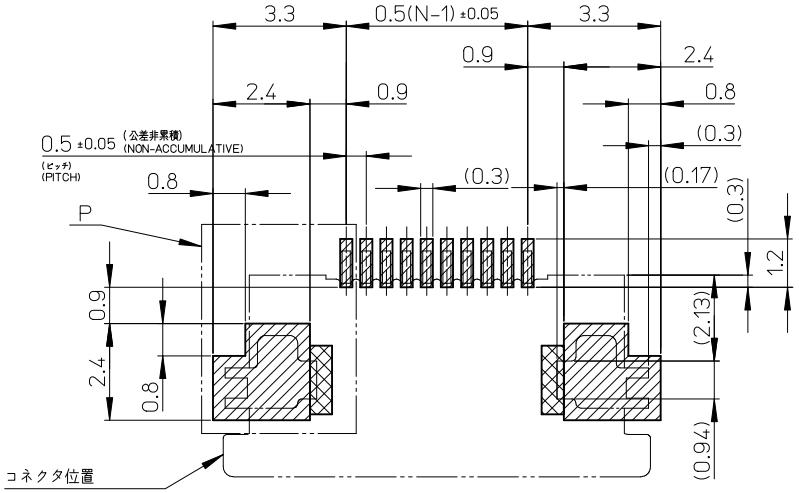
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	MM ONLY
SCALE	---
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY	MNABEI
DATE	'04/07/09
CHECKED BY	KTOJO
DATE	'04/07/09
APPROVED BY	NUKITA
DATE	'04/07/09
MATERIAL NO.	SEE TABLE
DOCUMENT NO.	SD-54104-077
SHEET NO.	1 OF 2
SIZE	A3

TITLE: 0.5 FPC CONN. ZIF SMT R/A UPPER CONTACT SEPARATED GOLD PLATING

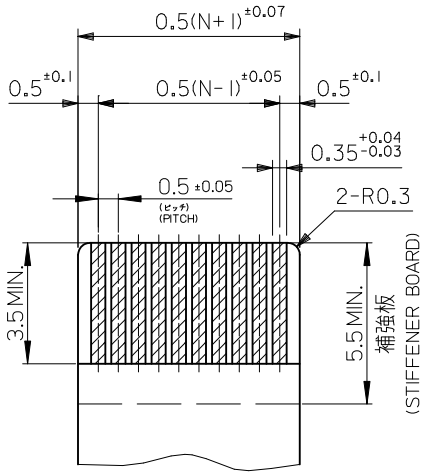
molex

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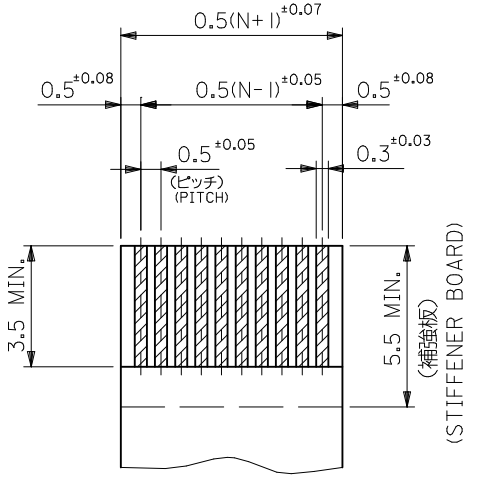
参考基板レイアウト
RECOMMENDED P.W.BOARD PATTERN DIMENSION(REF.)

(マウント面)
(MOUNTING SIDE)



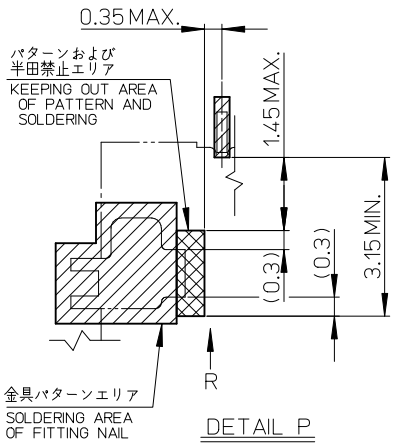
適合金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD PLATING
RECOMMENDED DIMENSION

(仕上がり厚さ : 0.3 ±0.03)
(THICKNESS : 0.3±0.03)

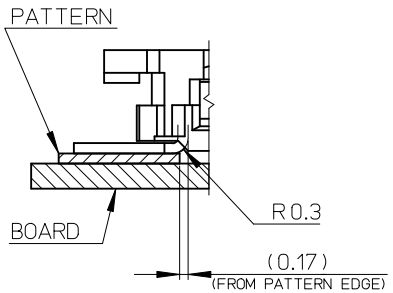


適合金めっきFFC推奨寸法
APPLICABLE FFC OF GOLD PLATING
RECOMMENDED DIMENSION

(仕上がり厚さ : 0.3 ±0.03)
(THICKNESS : 0.3±0.03)



DETAIL P



VIEW R
(DETAIL OF FITTING NAIL
ON PATTERN)

注記 NOTES

1.使用材料 MATERIAL
ハウジング : 46ナイロン、ガラス充填、UL94V-0、白
HOUSING:PA46,GLASS FILLED,UL94V-0,WHITE
アクチュエータ : ポリフェニレンサルファイド (PPS) 、ガラス充填、UL94V-0、茶色
ACTUATOR:POLYPHENYLENE SULFIDE,GLASS FILLED,UL94V-0,BROWN
ターミナル : リン青銅(t=0.2) 金メッキ コンタクト部 0.1 MICROMETER MINIMUM
テール部 0.05 MICROMETER MINIMUM
ニッケル下地 1.0 MICROMETER MINIMUM
TERMINAL PHOS-BRONZE GOLD-PLATING
CONTACT PORTION : 0.1 MICROMETER MINIMUM
TAIL PORTION : 0.05 MICROMETER MINIMUM
NICKEL PLATING : 1.0 MICROMETER MINIMUM
金具 : リン青銅(t=0.2) 錫メッキ 1.0~3.0 MICROMETER MINIMUM
ニッケル下地 1.0~3.0 MICROMETER MINIMUM
FITTING NAIL : PHOS-BRONZE TIN-PLATING 1.0~3.0 MICROMETER MINIMUM
OVER NICKEL 1.0~3.0 MICROMETER MINIMUM
2.エンボステープ梱包時はアクチュエータがロックした状態とする.
IN THE PACKAGE, ACTUATOR OF PART NO.54104-**29 SHOULD BE LOCKED.
3 ソルダーテール半田付け面のズレ量、および金具半田付け面のズレ量は
基準面 H に対し上方向 0.1MAXIMUM、下方向 0.15MAXIMUMとする.
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM H
UPPER DIRECTION : 0.1MAXIMUM, LOWER DIRECTION : 0.15 MAXIMUM.

4 偶数極に適用.
APPLY FOR EVEN CIRCUIT.
5 パターンは く 離止め金具.
FITTING NAIL FOR PREVENTION OF PEELING
OF P.W.BOARD PATTERN.
6.ELV & RoHS適合品
ELV AND RoHS COMPLIANT

FPC/FFCについて :
打ち抜き方向は導体側から補強板側を推奨いたします.
導体部は軟銅箔 35MICROMETER または 50MICROMETERを推奨いたします.
RECOMMENDED PUNCHER DIRECTION
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED CONDUCTOR SPEC
THICKNESS OF SOFT COPPER FOIL
: 35MICROMETERS OR 50MICROMETERS
FPCについて :
補強フィルム材質はポリイミドを推奨いたします.
接着剤は熱硬化接着剤を推奨いたします.
RECOMMENDED MATERIAL
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

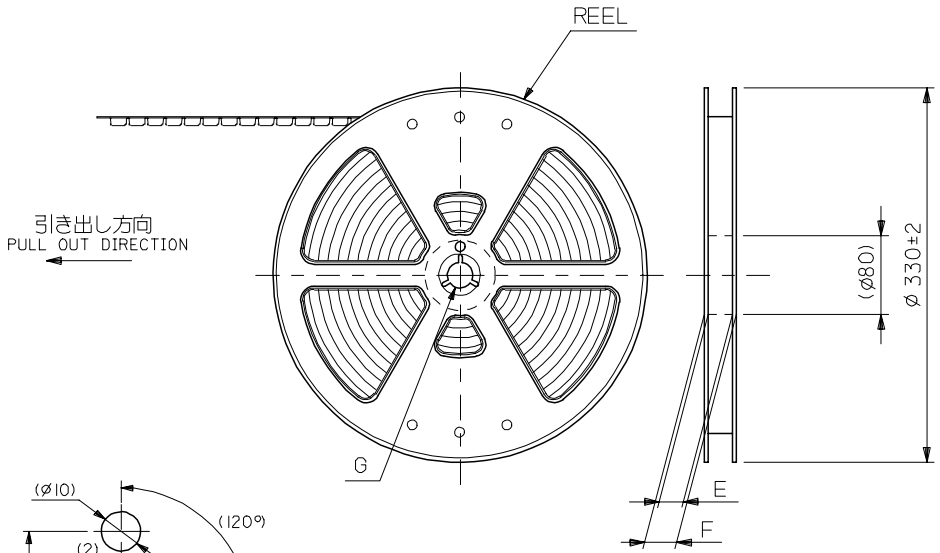
REVISED
EC NO: J2012-1496 2012/06/12
DRWN:KNAGUMO 2012/06/12
CH'KD:KTAKAHASHI 2012/06/12
APPR:KMORIKAWA 2012/06/12
DESCRIPTION
REV

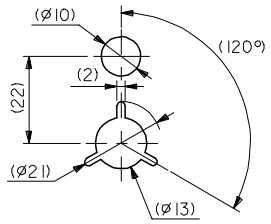
GENERAL TOLERANCES
(UNLESS SPECIFIED)

10 UNDER	±---
10 OVER 30 UNDER	±---
30 OVER	±---
ANGULAR	±--- °

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY	SCALE: ---	DESIGN UNITS: METRIC	THIRD ANGLE PROJECTION
DRAWN BY: MNABEI	DATE: '04/07/09	TITLE: 0.5 FPC CONN. ZIF SMT R/A UPPER CONTACT SEPARATED GOLD PLATING	
CHECKED BY: KTOJO	DATE: '04/07/09		
APPROVED BY: NUKITA	DATE: '04/07/09	molex	
MATERIAL NO.: SEE SHEET 1 OF 2		DOCUMENT NO.: SD-54104-077	SHEET NO.: 2 OF 2
SIZE: A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

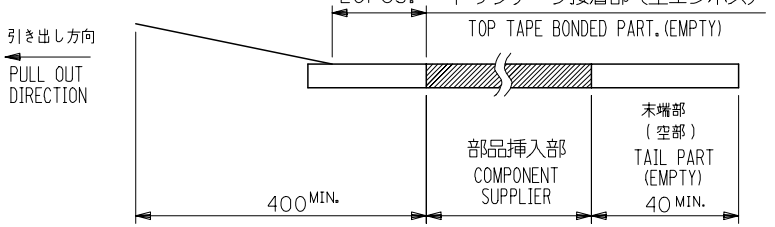




DETAIL G

NOTES

1. 梱包数量：１５００個／リール
   NUMBER OF CONNECTORS : 1500PCS/REEL
2. リードテープ長さ LEAD TAPE LENGTH



3. 材料(MATERIAL)
   キャリアテープ(CARRIER TAPE)：ポリプロピレン(POLYPROPYLENE)
   トップテープ(TOPTAPE)：PET , PE , PEF
   リール(REEL)：ポリスチレン (POLYSTYLENE)

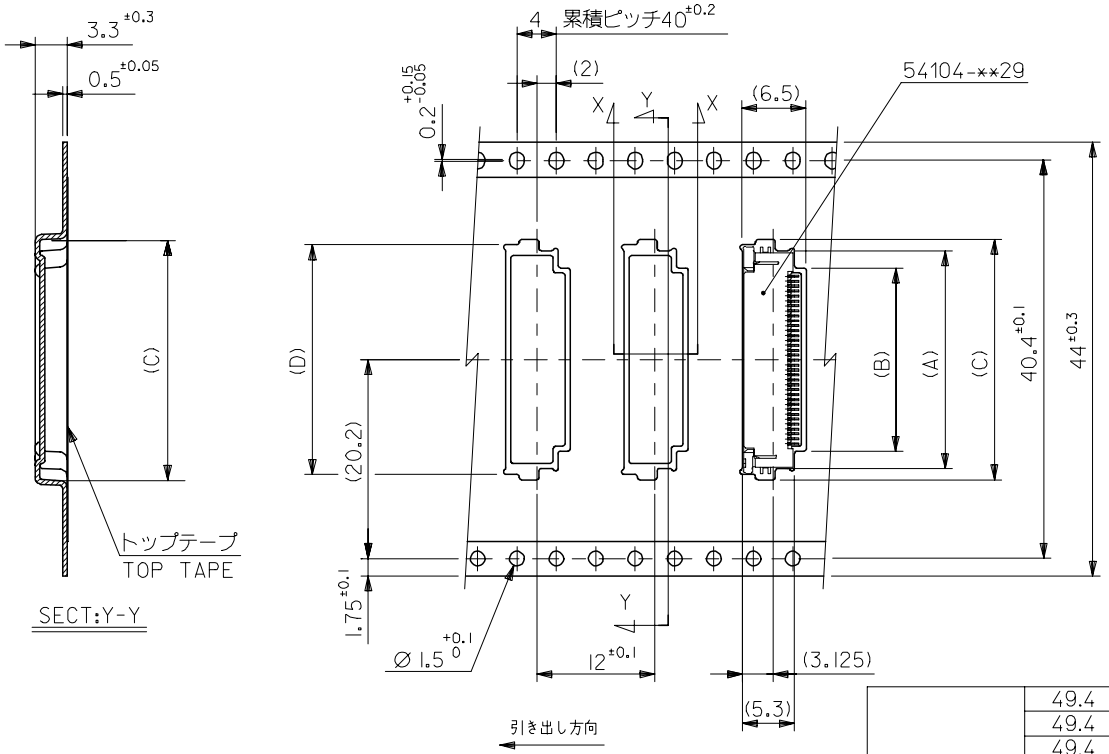
4. 本製品は 54104-**96 のターミナル部分金メッキ品である。

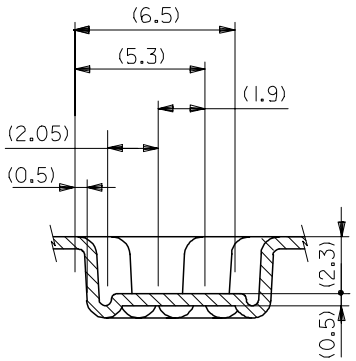
REVISED				REV	DESCRIPTION
EC NO: J2007-2009	DRWN:TYAMADA01	2007/01/23			
	CHKD:KTOYODA	2007/01/25			
	APPR:NUKITA	2007/01/25			
B					

GENERAL TOLERANCES (UNLESS SPECIFIED)	
10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR ±3 °	

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY	SCALE: 2:1	DESIGN UNITS: METRIC	THIRD ANGLE PROJECTION
DRAWN BY: MNABE I — DATE: '04/07/09	TITLE: EMBOSSED TAPE PACKAGE FOR 54104-**29 -LEAD FREE-		
CHECKED BY: KTOJO — DATE: '04/07/09			
APPROVED BY: NUKITA — DATE: '04/07/09	molex MOLEX INCORPORATED		
MATERIAL NO.: SEE CHART	DOCUMENT NO.: SD-54104-078	SHEET NO.: 1 OF 2	
SIZE: A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		





44	49.4	45.4	30.8	31.9	26.1	29.6	54104-5031	50
	49.4	45.4	28.8	29.9	24.1	27.6	54104-4631	46
	49.4	45.4	28.3	29.4	23.6	27.1	54104-4531	45
	49.4	45.4	27.8	28.9	23.1	26.6	54104-4431	44
	49.4	45.4	27.3	28.4	22.6	26.1	54104-4331	43
	49.4	45.4	25.8	26.9	21.1	24.6	54104-4031	40
	49.4	45.4	24.8	25.9	20.1	23.6	54104-3831	38
	49.4	45.4	23.8	24.9	19.1	22.6	54104-3631	36
	49.4	45.4	23.3	24.4	18.6	22.1	54104-3531	35
	49.4	45.4	22.8	23.9	18.1	21.6	54104-3431	34
	49.4	45.4	22.3	23.4	17.6	21.1	54104-3331	33
	49.4	45.4	21.8	22.9	17.1	20.6	54104-3231	32
	49.4	45.4	20.8	21.9	16.1	19.6	54104-3031	30
キャリアテープ幅 CARRIER TAPE WIDTH	F	E	D	C	B	A	MATERIAL NO.	CKT.

REVISED
EC NO: J2007-2009 2007/01/23
DRWN:TYAMADA01 2007/01/25
CHKD:KTOYODA
APPR:NUKITA
DESCRIPTION
REV B

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR ±3 °	

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: 2:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: MNABE I DATE: '04/07/09
CHECKED BY: KTOJO DATE: '04/07/09
APPROVED BY: NUKITA DATE: '04/07/09

TITLE: EMBOSSED TAPE PACKAGE FOR 54104-**29 -LEAD FREE-

molex MOLEX INCORPORATED

MATERIAL NO.: SEE CHART
DOCUMENT NO.: SD-54104-078
SHEET NO.: 2 OF 2

SIZE A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION